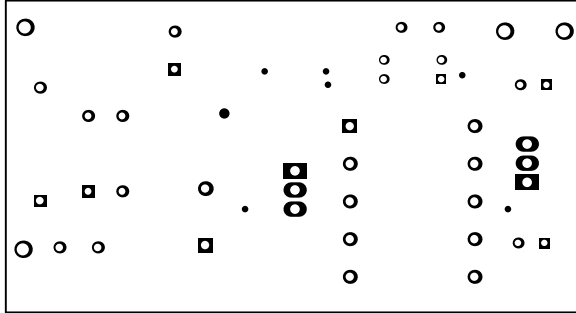
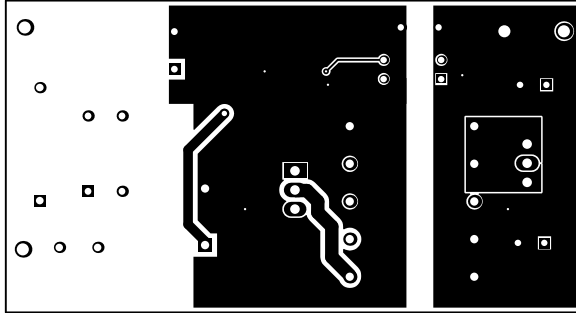


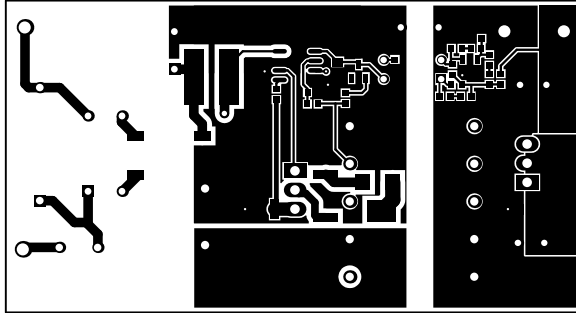
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/30/2014 8:43:07 AM	TEXAS INSTRUMENTS	



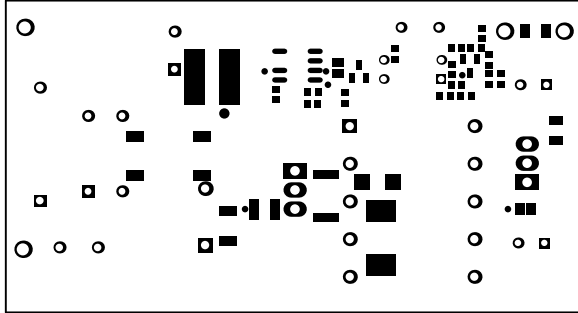
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/30/2014 8:43:08 AM	TEXAS INSTRUMENTS	



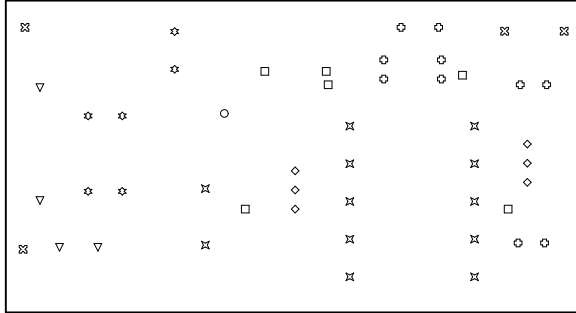
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/30/2014 8:43:08 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/30/2014 8:43:09 AM	TEXAS INSTRUMENTS	



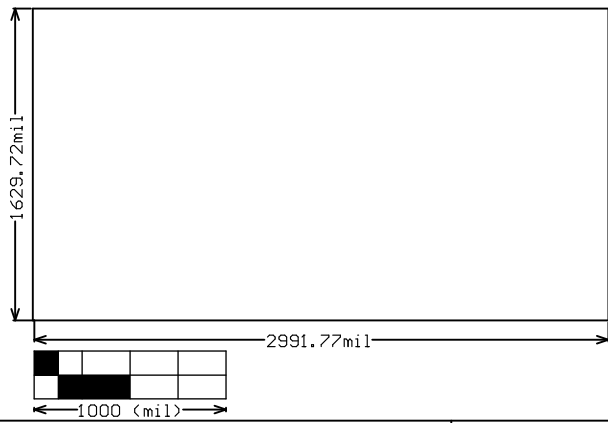
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/30/2014 8:43:10 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	6	12mil (0.305mm)	PTH	Round
○	1	28mil (0.711mm)	PTH	Round
⊗	10	33.465mil (0.85mm)	PTH	Round
☆	6	35.433mil (0.9mm)	PTH	Round
▽	4	39.37mil (1mm)	PTH	Round
×	12	43.307mil (1.1mm)	PTH	Round
◇	6	50mil (1.27mm)	PTH	Round
⊗	4	63mil (1.6mm)	PTH	Round
	49 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/30/2014 8:43:11 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9144	REV: C	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/30/2014 8:43:12 AM	TEXAS INSTRUMENTS	

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